

WHAT IS CLAIMED IS:

1. A circuit board comprising:
 - a core plate;
 - a buildup layer including insulation layers and
 - 5 conductor layers alternately stacked on each other; and
 - a deformation-interrupting section extending
 - through the insulation layers between the conductor
 - layers in contact with the conductor layers, the
 - deformation-interrupting section being formed of
 - 10 a material having a lower thermal expansion coefficient
 - and a higher Young's modulus than the insulation
 - layers, the deformation-interrupting section
 - interrupting deformation of the insulation layers when
 - there is a change in ambient temperature or an external
 - 15 force is applied to the circuit board.
2. The circuit board according to claim 1,
wherein the deformation-interrupting section is formed
of an insulator.
3. The circuit board according to claim 2,
20 wherein the insulator is made of ceramic.
4. The circuit board according to claim 1,
wherein the deformation-interrupting section is formed
of a conductor.
5. The circuit board according to claim 4,
25 wherein the conductor is formed of a material selected
from the group consisting of Sn-Pb alloy solder,
lead-free solder, Mo paste and W paste.

6. A method of forming a circuit board
comprising:

forming an first inner conductor layer on a core
plate;

5 forming an first interlevel insulator layers on
the inner conductor layer;

forming a hole through the first interlevel
insulator layers;

filling the hole with an insulator or a conductor,
10 thereby forming a deformation-interrupting section, the
insulator or the conductor having a lower thermal
expansion coefficient and a higher Young's modulus than
the first interlevel insulator layers;

forming an second inner conductor layer on the
15 first interlevel insulator layers with the deformation-
interrupting section;

forming a buildup layer having the interlevel
insulator layers and the inner conductor layers are
alternately stacked upon each other; and

20 forming the wire or the electrode on the buildup
layer.

7. The method according to claim 6, wherein
a ceramic paste is used as a material of the
deformation-interrupting section.

25 8. The method according to claim 6, wherein
a material selected from the group consisting of Sn-Pb
alloy solder, lead-free solder, Mo paste and W paste is

used as a material of the deformation-interrupting section.